

HOSTAFORM® S 9243 XAP® 2 LS

HOSTAFORM®

POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than the basic type HOSTAFORM® C 9021 Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Preliminary Datasheet for natural and colored grades

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	4 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage range, parallel	1.9 %	ISO 294-4, 2577
Moulding shrinkage range, normal	1.8 %	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	1950 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	44 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9 %	ISO 527-1/-2
Nominal strain at break	40 %	ISO 527-1/-2
Flexural modulus	1850 MPa	ISO 178
Tensile creep modulus, 1h	1700 MPa	ISO 899-1
Tensile creep modulus, 1000h	950 MPa	ISO 899-1
Charpy impact strength, 23 °C	N kJ/m ²	ISO 179/1eU
Charpy impact strength, -30 °C	200 ^[P] kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23 °C	15 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30 °C	9 kJ/m ²	ISO 179/1eA
Poisson's ratio	0.4 ^[C]	

[P]: Partial Break

[C]: Calculated

Thermal properties

Melting temperature, 10 °C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	75 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120 E-6/K	ISO 11359-1/-2

Flammability

Burning rate, Thickness 1 mm	48.9 mm/min	ISO 3795 (FMVSS 302)
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Electrical properties

Relative permittivity, 100Hz	3.8	IEC 62631-2-1
Relative permittivity, 1MHz	3.8	IEC 62631-2-1
Dissipation factor, 100Hz	30 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	60 E-4	IEC 62631-2-1
Volume resistivity	1E11 Ohm.m	IEC 62631-3-1
Surface resistivity	1E13 Ohm	IEC 62631-3-2

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Comparative tracking index	600	IEC 60112
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Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	1 %	Sim. to ISO 62
Density	1330 kg/m ³	ISO 1183

Injection

Drying Temperature	120 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.15 %
Screw tangential speed	≤0.202 m/s
Min. mould temperature	60 °C
Max. mould temperature	80 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa

Characteristics

Additives	Release agent
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Additional information

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granules

Storage

The product can then be stored in standard conditions until processed.